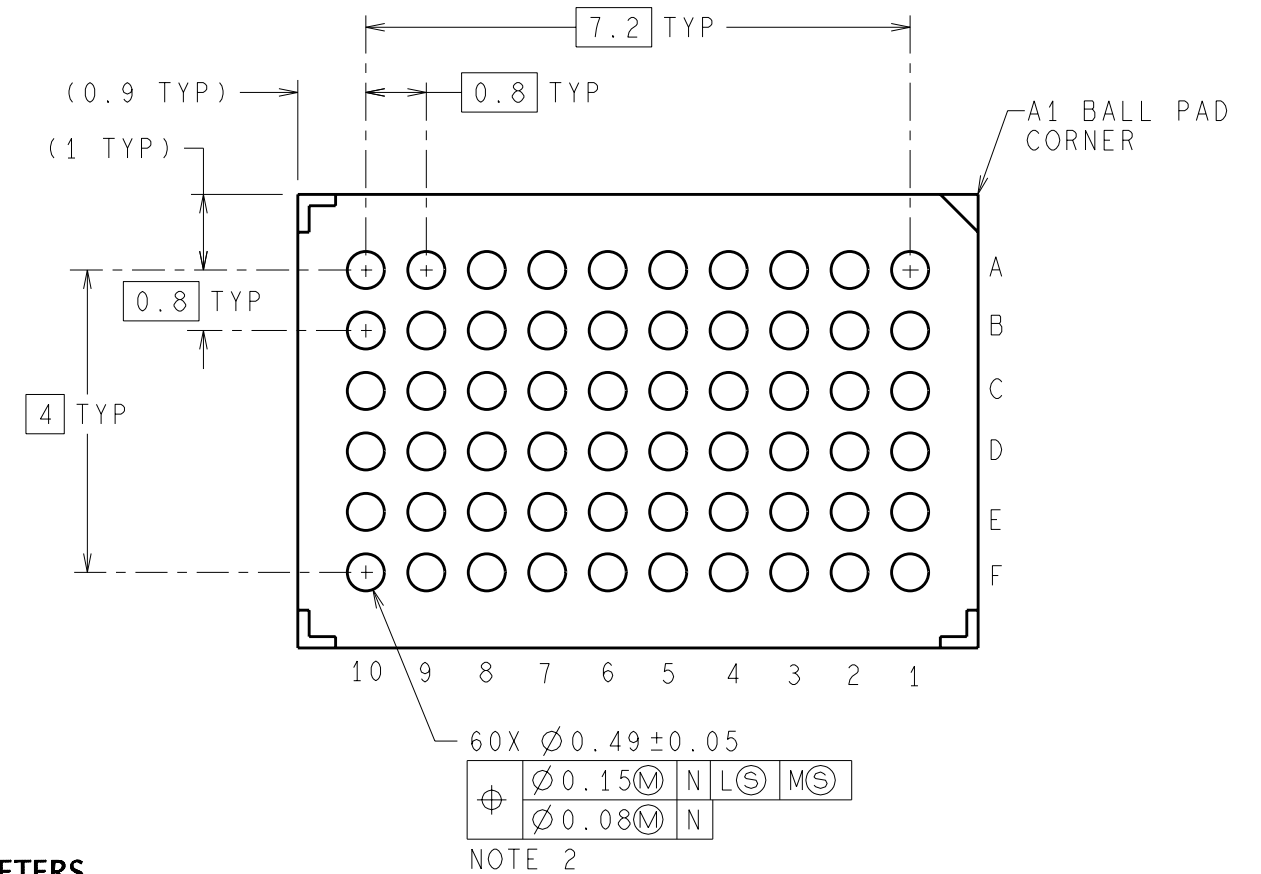
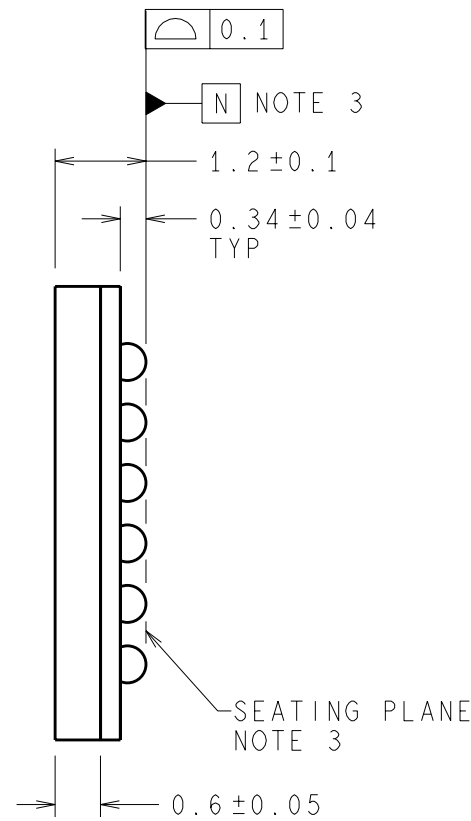
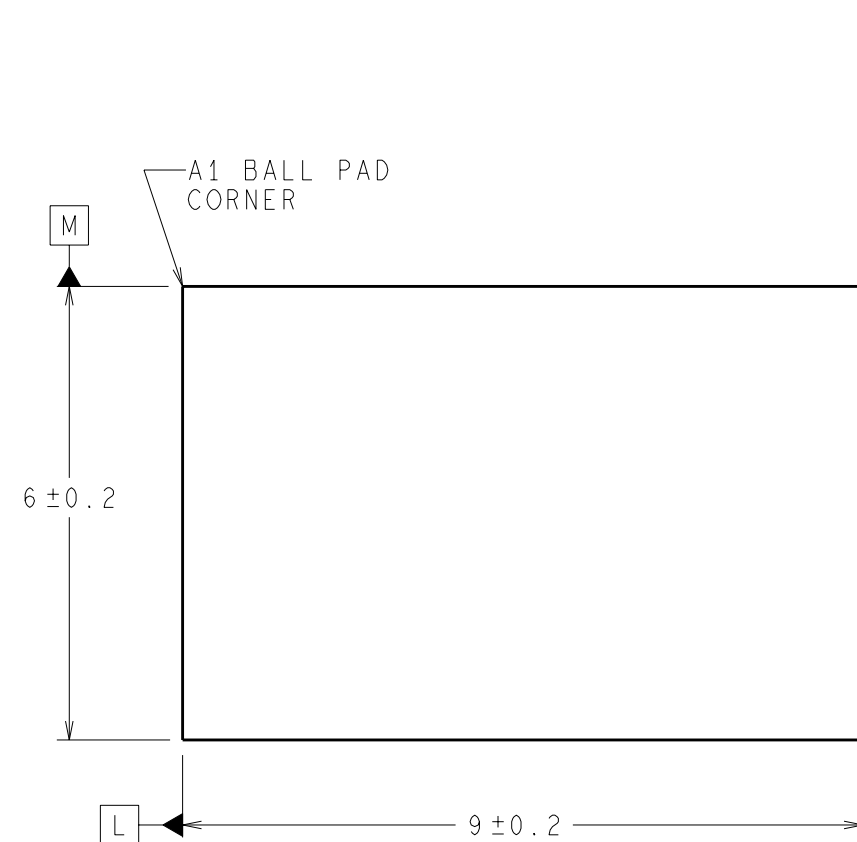


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	1258	10/23/2003	TL/AP



**DIMENSIONS ARE IN MILLIMETERS**  
DIMENSIONS IN ( ) FOR REFERENCE ONLY

Φ	Ø 0.15 (M)	N	L (S)	M (S)
	Ø 0.08 (M)	N		

NOTE 2

NOTES: UNLESS OTHERWISE SPECIFIED

- FOR SOLDER BUMP COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE ([www.national.com](http://www.national.com)).
- DIMENSION MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
- PRIMARY DATUM N AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- NO JEDEC REGISTRATION AS OF OCTOBER 2003.

APPROVALS		DATE	 2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DRAWN	T. LEQUANG	10/23/2003			
DFTG. CHK.	MARTA SUCHY	10/23/2003	<b>FBGA, PLASTIC, LAMINATE,</b> <b>9 X 6 X 1.2mm,</b> <b>60 BALL, 0.8mm PITCH</b>		
ENGR. CHK.	ANINDYA PODDAR	10/23/2003			
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
 MM		NTS	B	(SC)MKT-SLF60A	A
FORMERLY: N/A		SHEET 1 of 1			